



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Chopra et al.

Serial No.: 10/620,002

Filed: July 14, 2003

For: SLURRY FOR USE WITH FIXED-
ABRASIVE POLISHING PADS IN
POLISHING SEMICONDUCTOR DEVICE
CONDUCTIVE STRUCTURES THAT
INCLUDE COPPER AND TUNGSTEN

Confirmation No.: 7481

Examiner: L. Umez-Eronini

Group Art Unit: 1765

Attorney Docket No.: 2269-4373.2US
(00-0036.02/US)

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EV 826302950 US

Date of Deposit with USPS: December 4, 2006

Person making Deposit: Brett Hooke

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

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Commissioner for Patents
P.O. Box 1450
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Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 or PTO/SB/08 be considered by the Examiner and made of record. Copies of any cited foreign patents, publications, or pending unpublished U.S. applications are enclosed pursuant to 37 C.F.R. § 1.98(a)(2).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

Other Documents

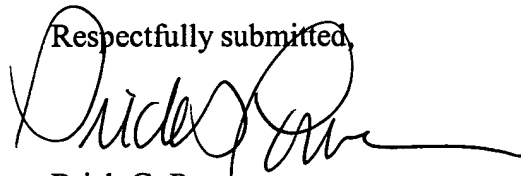
GUTMANN, ET AL., Chemical-mechanical polishing of copper with oxide and polymer interlevel dielectrics, Thin Solid Films 270:596-600 (1995).

ZEIDLER, ET AL., The interaction between different barrier metals and the copper surface during the chemical-mechanical polishing, Microelectronic Engineering 37/38:237-249 (1997).

Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is believed to be filed before the mailing date of the first Office Action on the merits subsequent to the filing of an RCE in the above-identified application.

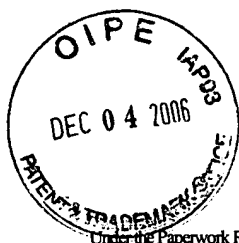
Respectfully submitted,



Brick G. Power
Registration No. 38,581
Attorney for Applicant(s)
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: December 4, 2006
BGP/nj:eg

Enclosures: Form PTO-1449 or PTO/SB/08
Cited Non-U.S. Patent Documents



PTO/SB/08B(10-03)

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Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet

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of

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Complete if Known

Application Number	10/620,002
Filing Date	July 14, 2003
First Named Inventor	Chopra et al.
Group Art Unit	1765
Examiner Name	L. Umez-Eronini
Attorney Docket Number	2269-4373.2US (00-0036.02/US)

NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		GUTMANN, ET AL., Chemical-mechanical polishing of copper with oxide and polymer interlevel dielectrics, Thin Solid Films 270:596-600 (1995).	
		ZEIDLER, ET AL., The interaction between different barrier metals and the copper surface during the chemical-mechanical polishing, Microelectronic Engineering 37/38:237-249 (1997).	

Examiner
SignatureDate
Considered

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Unique citation designation number (optional). ² Applicant is to place a check mark here if English language Translation is attached.

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